

IN THE CLAIMS:

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1. (Original) A laminate comprising a combination of a metal layer with an insulating layer, said laminate having a layer construction of first metal layer/insulating layer/second metal layer or a layer construction of metal layer/insulating layer, wherein

said insulating layer has a multilayer structure of two or more layers,

the layer on the side of the adhesive interface with the metal layer, out of the layers constituting the insulating layer, is a thermoplastic resin layer, and

the minimum value of the storage modulus at a temperature at or above  $T_g$  of the thermoplastic resin layer is not more than  $10^6$  Pa.

2. (Original) The laminate according to claim 1, wherein at least one layer constituting the insulating layer is formed of a polyimide resin or is a polyimide film.

3. (Original) The laminate according to claim 1, wherein all the layers constituting the insulating layer each are formed of a polyimide resin or are a polyimide film.

4. (Original) The laminate according to claim 1, wherein the metal layers each are formed of a material selected from the group consisting of copper alloy, copper, and stainless steel and the material constituting the first metal layer is the same as or different from the material constituting the second metal layer.

5. (Canceled)

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contd

6. (Original) An insulating film comprising: a resin film or a resin layer as an insulating layer; and, provided on both sides or one side of the insulating layer, a thermoplastic resin layer having a minimum value of the storage modulus of not more than  $10^6$  Pa at a temperature at or above  $T_g$  of the thermoplastic resin layer.

7. (Original) The insulating film according to claim 6, wherein at least one layer constituting the insulating layer is a polyimide film or is formed of a polyimide resin.

8. (Original) The insulating film according to claim 6, wherein all the layers constituting the insulating layer each are a polyimide film or are formed of a polyimide resin.

9. (Original) A laminate comprising a metal and an insulating film, said laminate being produced by using the insulating film according to claim 6.

10.-12. (Canceled)

13. (New) A method for producing an electronic circuit comprising the steps of:

\_\_\_\_\_ providing a laminate comprising a combination of a metal layer with an insulating layer, said laminate having a layer construction of first metal layer/insulating layer/second metal layer or a layer construction of metal layer/insulating layer, the insulating layer having a multilayer structure of two or more layers, the layer on the side of the adhesive interface with the metal layer, out of the layers constituting the insulating layer, being a thermoplastic resin layer, and a maximum value of the storage modulus at a temperature at or above T<sub>g</sub> of the thermoplastic resin layer being not more than 10<sup>6</sup> Pa;

\_\_\_\_\_ forming a photosensitive resin layer on a surface of the metal layer of the laminate; and

\_\_\_\_\_ patterning the thus formed photosensitive resin layer to prepare an electronic circuit.

14. (New) A method for producing an electronic circuit comprising the steps of:

providing an insulating film comprising an insulating layer and a thermoplastic resin layer provided on at least one side of the insulating layer, the thermoplastic resin having a maximum value of the storage modulus of not more than  $10^6$  Pa at a temperature at or above  $T_g$  of the thermoplastic resin layer;

laminating the insulating film with a metal layer to prepare a laminate;

forming a photosensitive resin layer on a surface of the metal layer of the laminate; and

patterning the thus formed photosensitive resin layer to prepare an electronic circuit.